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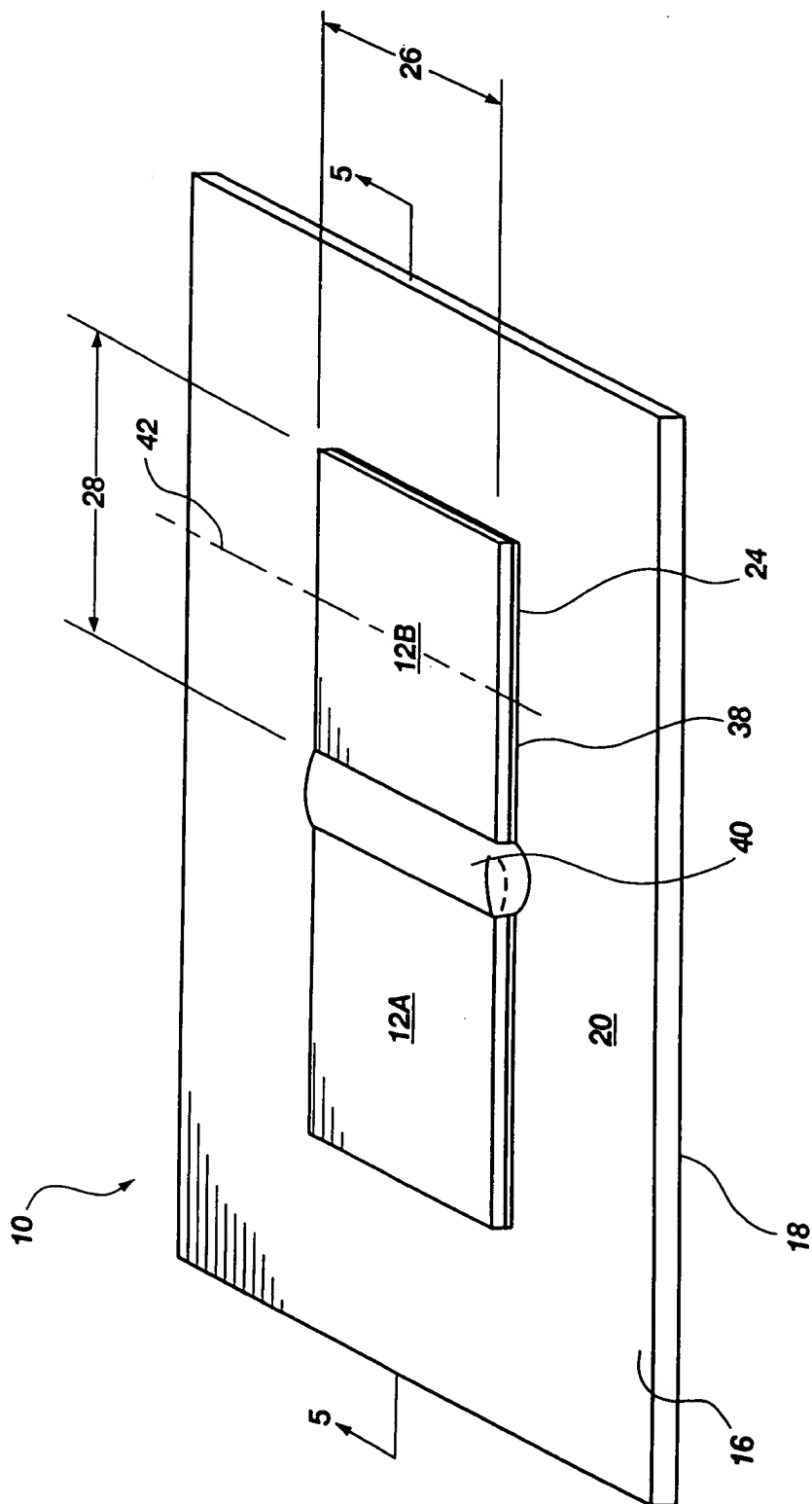


Fig. 1

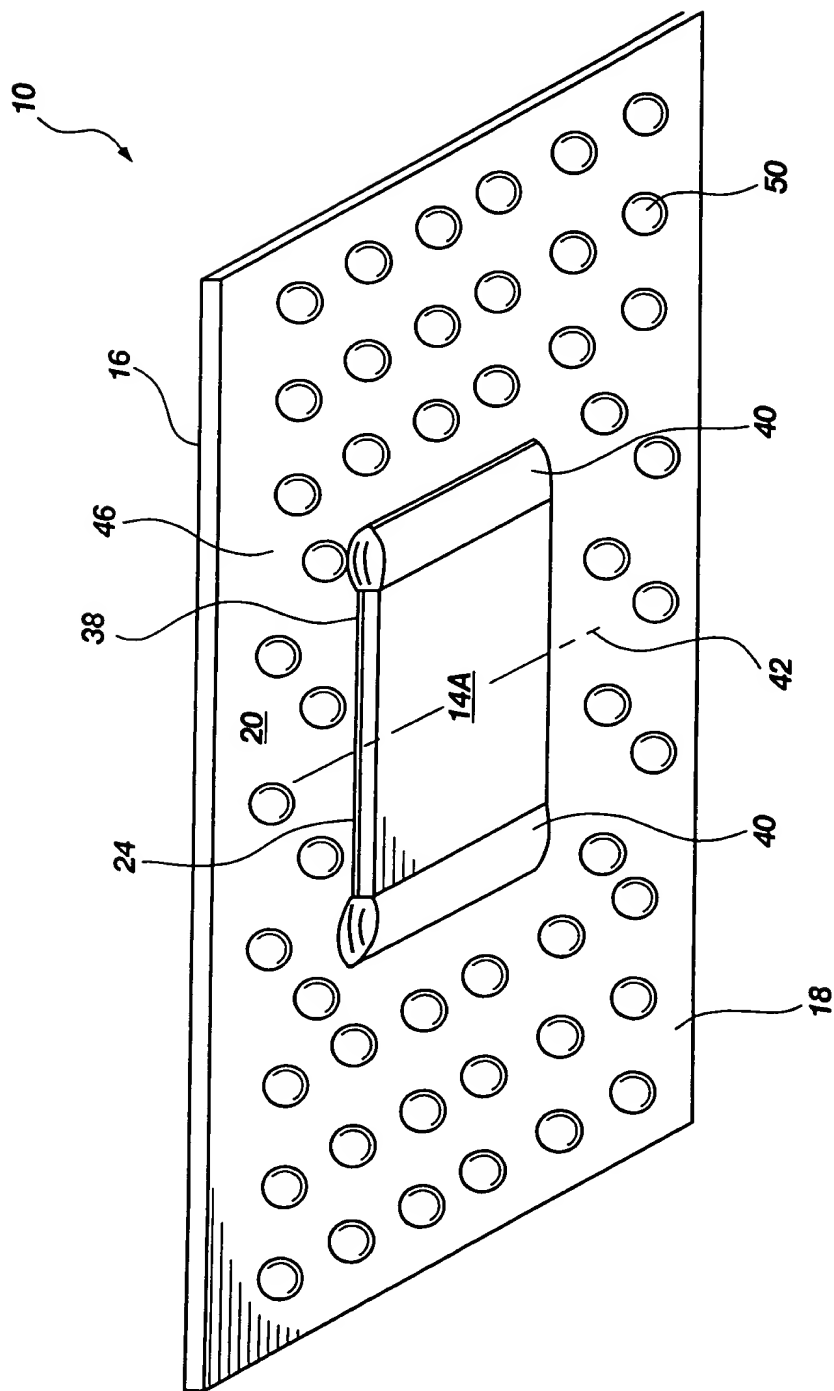
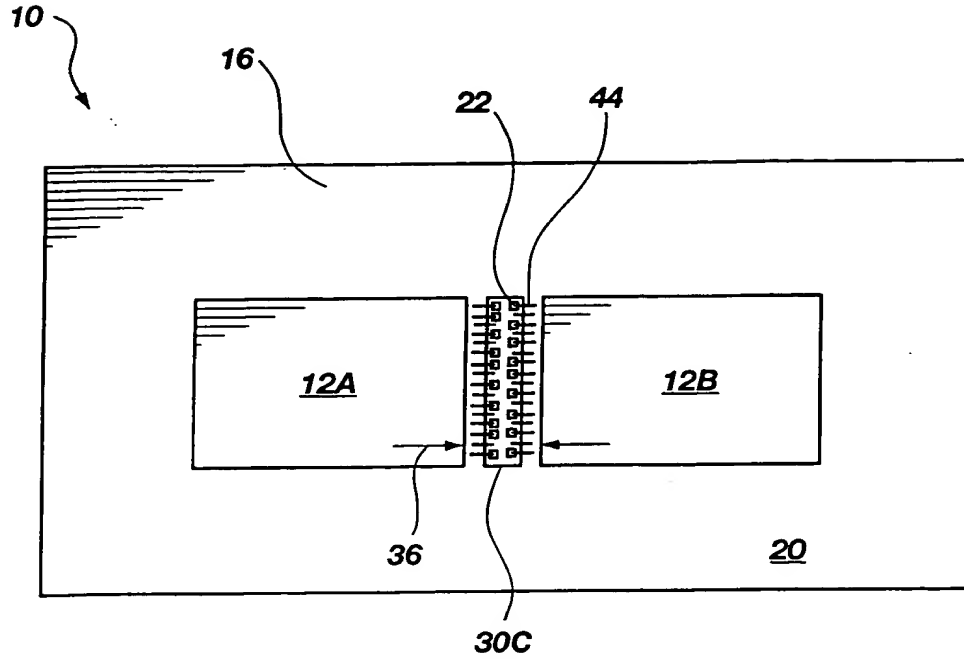


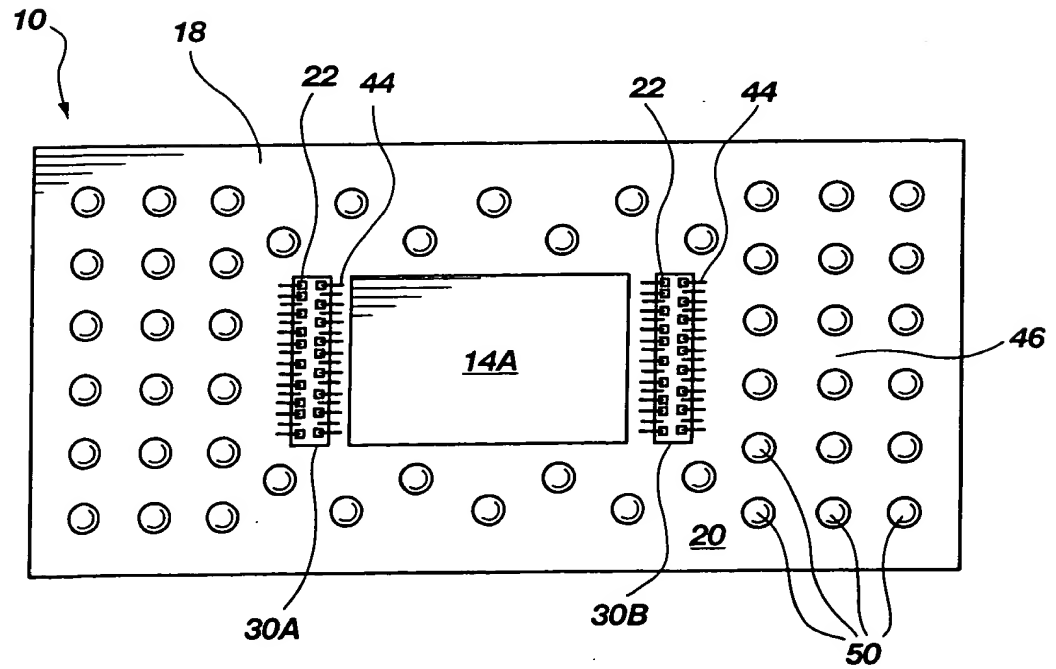
Fig. 2



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**Fig. 3**



**Fig. 4**

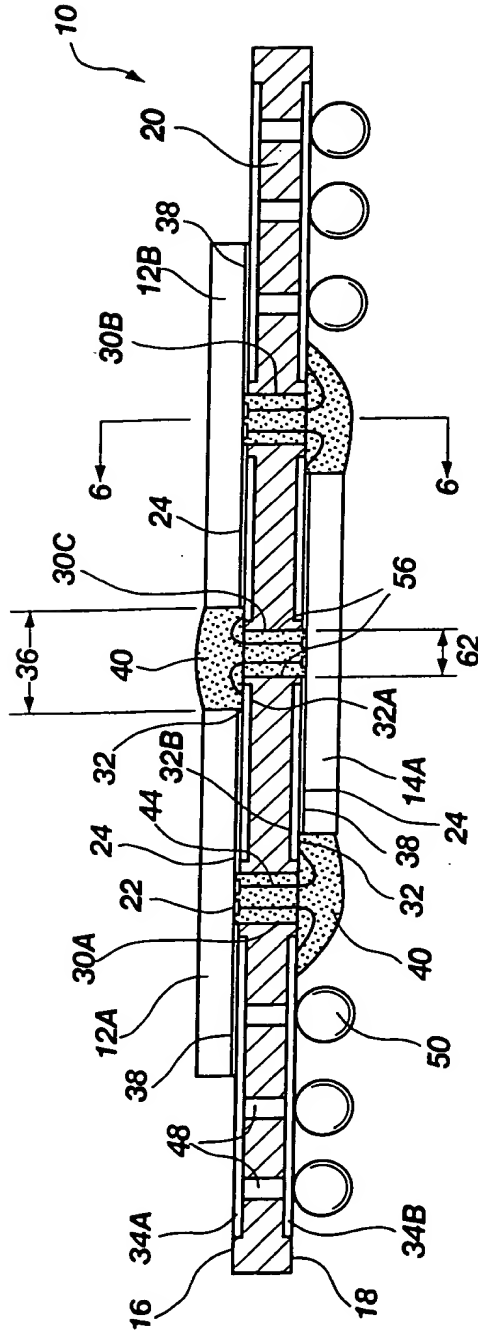


Fig. 5

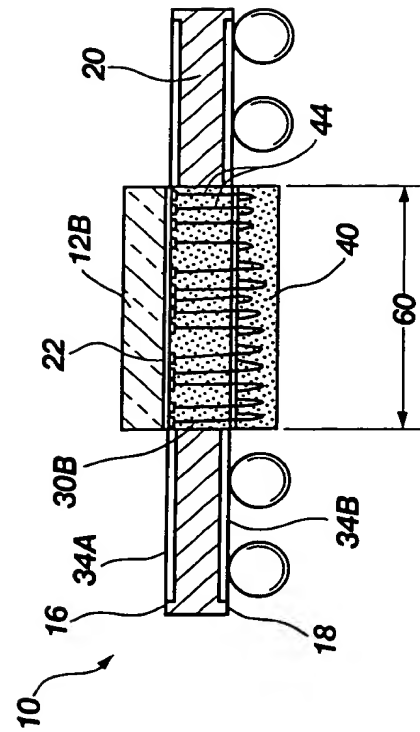
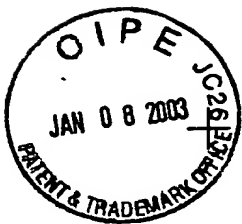


Fig. 6



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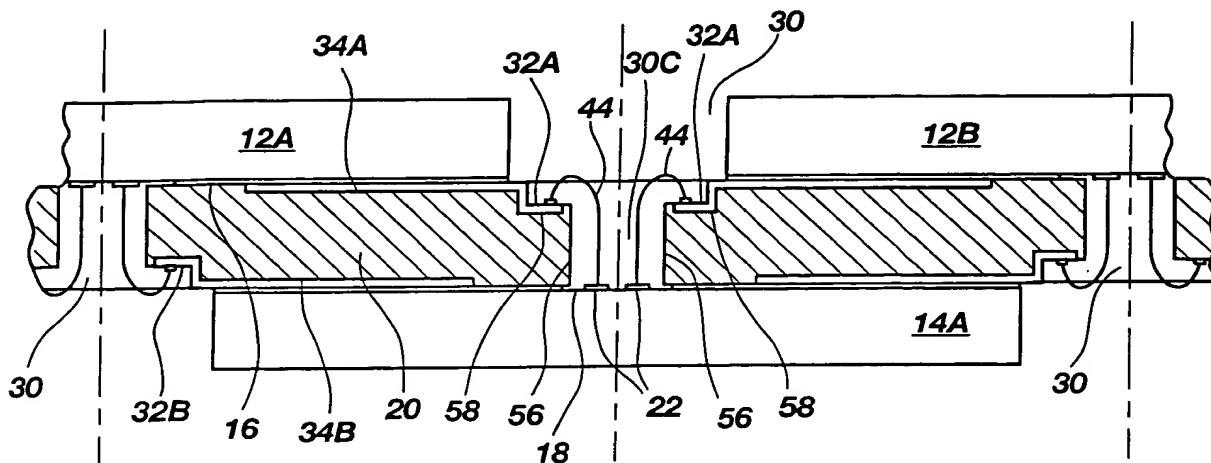


Fig. 7

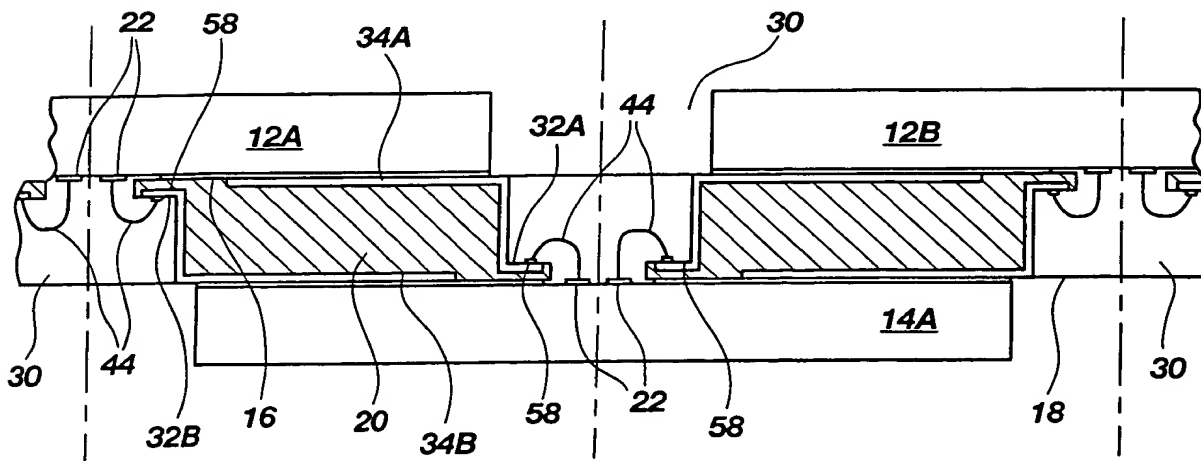


Fig. 8



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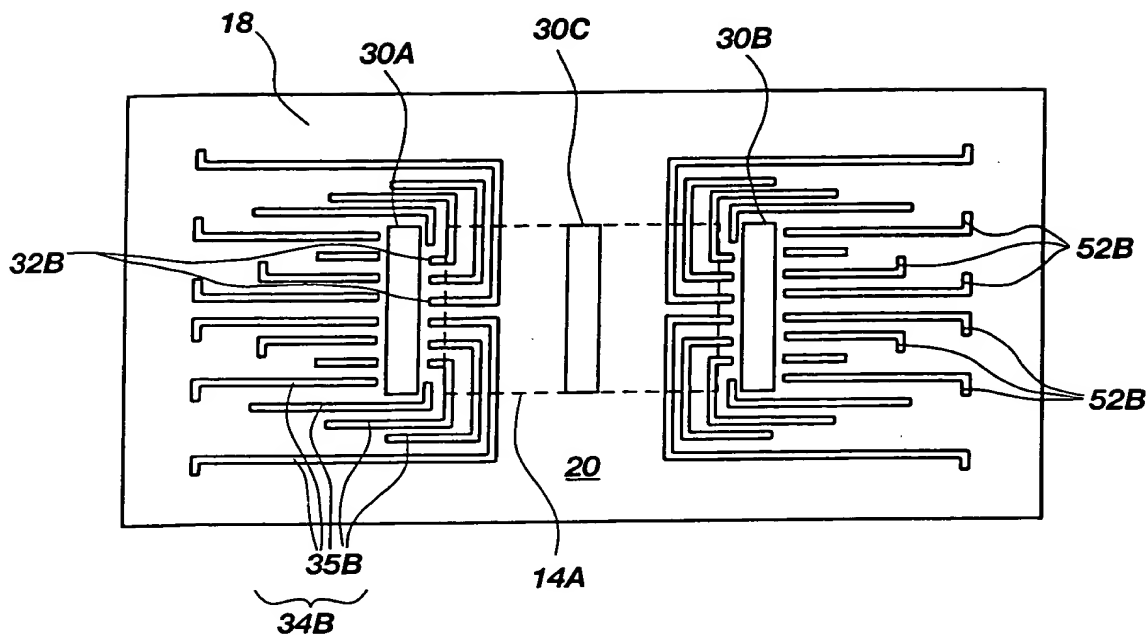


Fig. 10

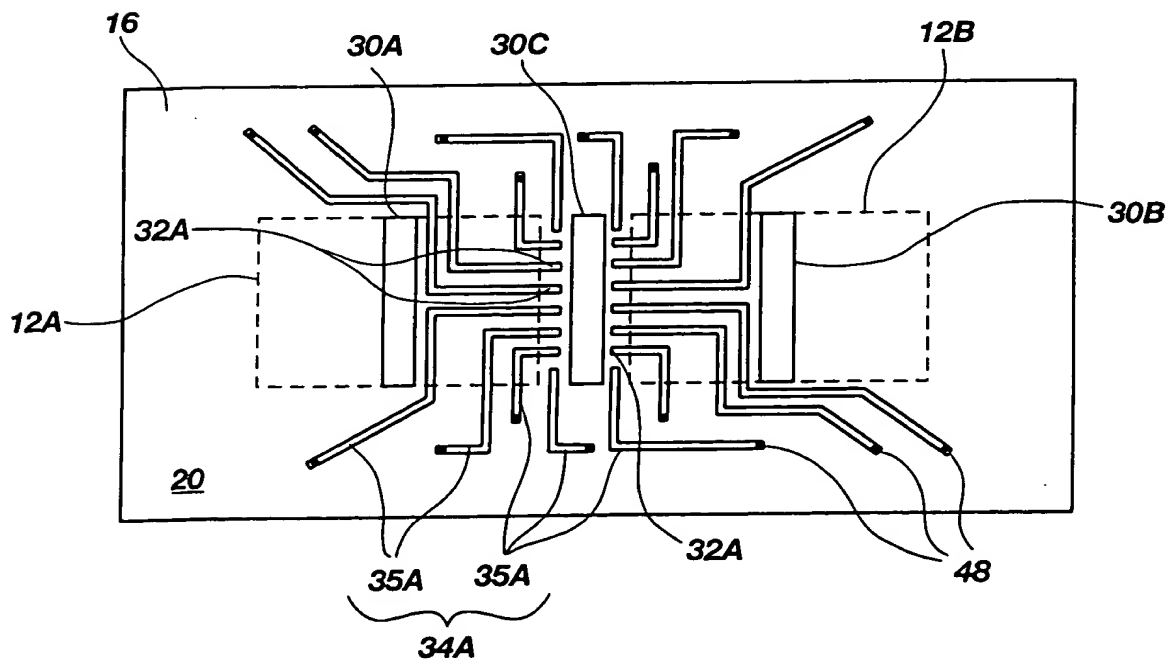


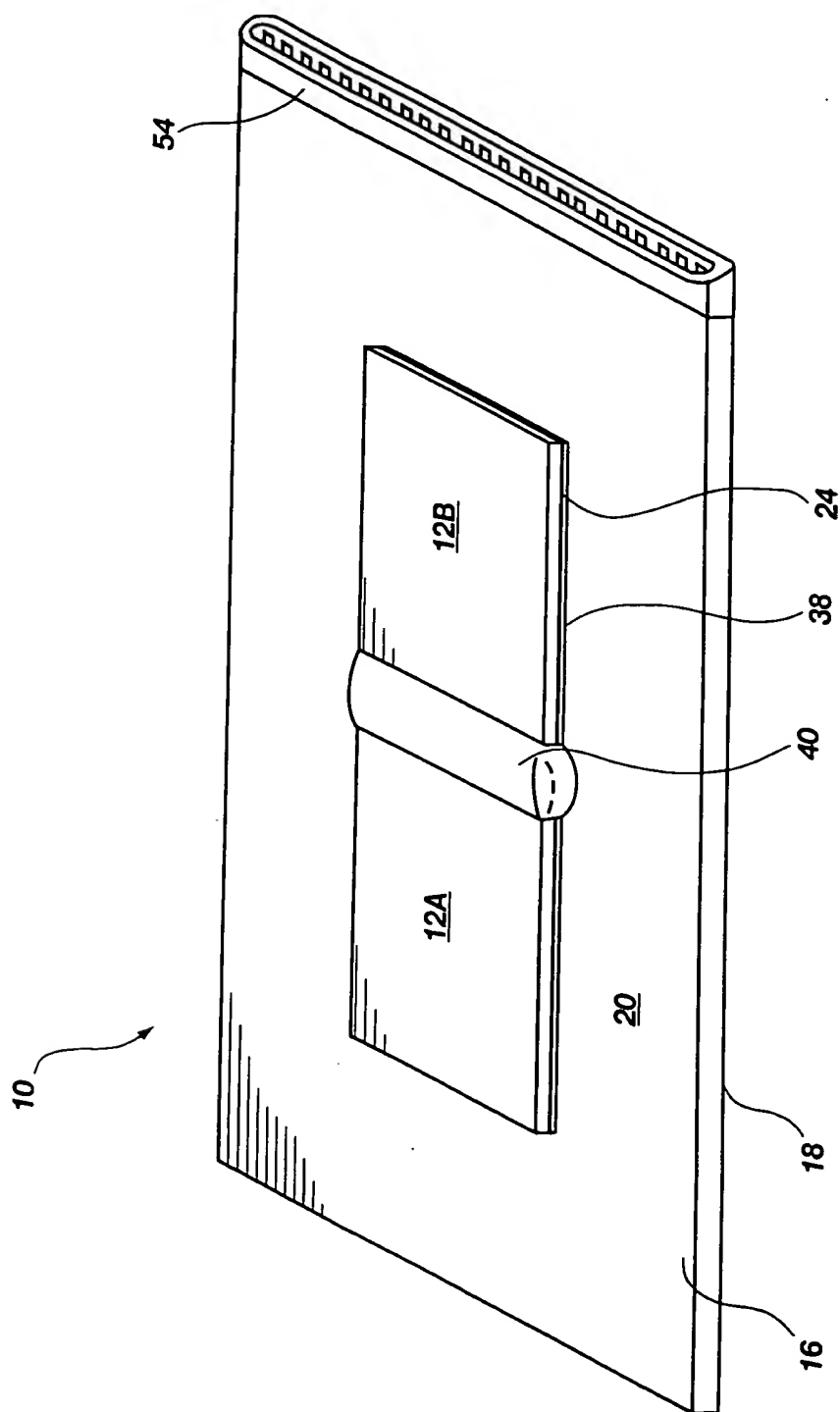
Fig. 9

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**TITLE: HIGH DENSITY MODULARITY FOR IC'S**  
Inventor: Salman Akram  
Serial No.: 09/241,177  
Docket No.: 3638US (98-0093)

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**Fig. 11**

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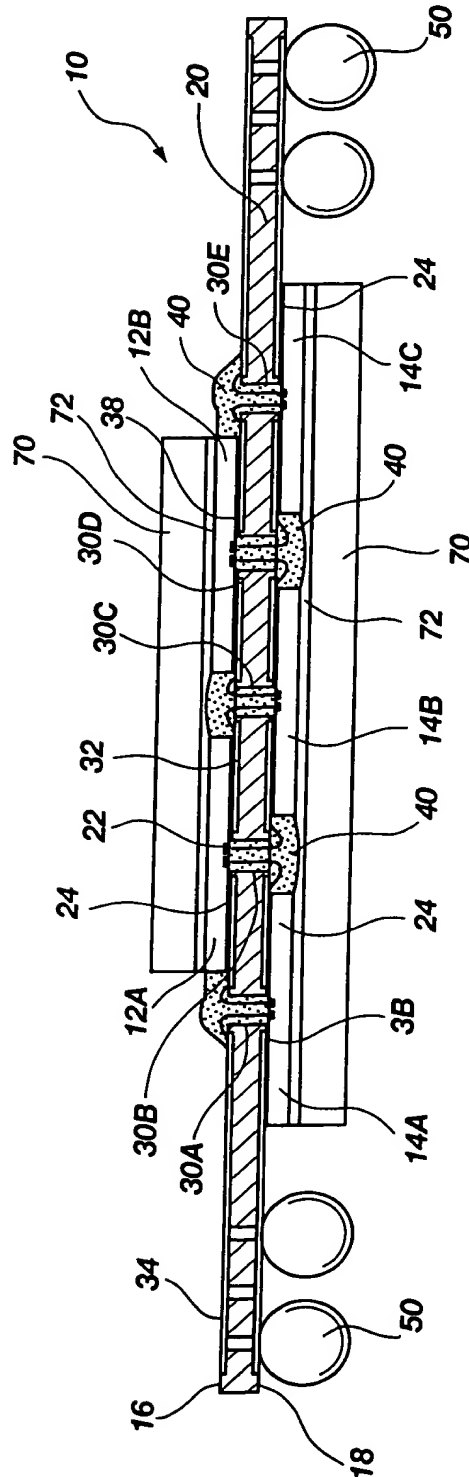
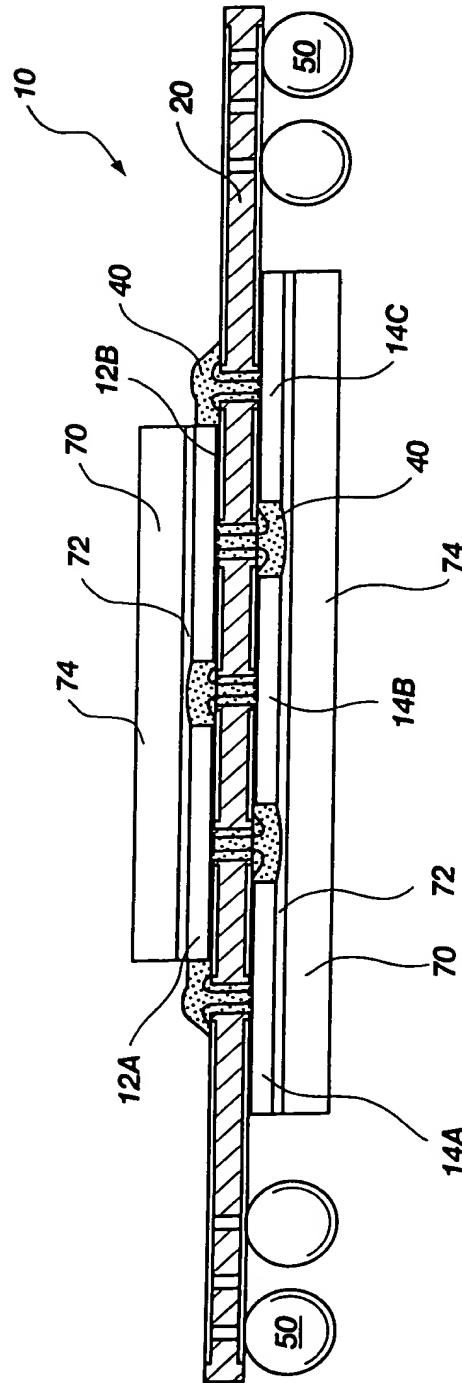


Fig. 12





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**Fig. 13**

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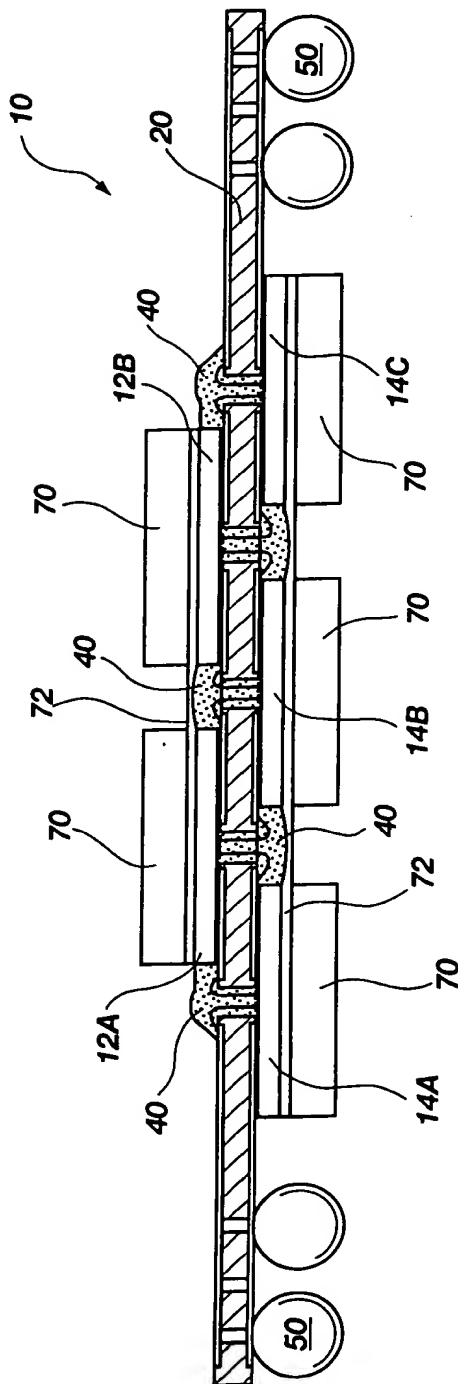


Fig. 14



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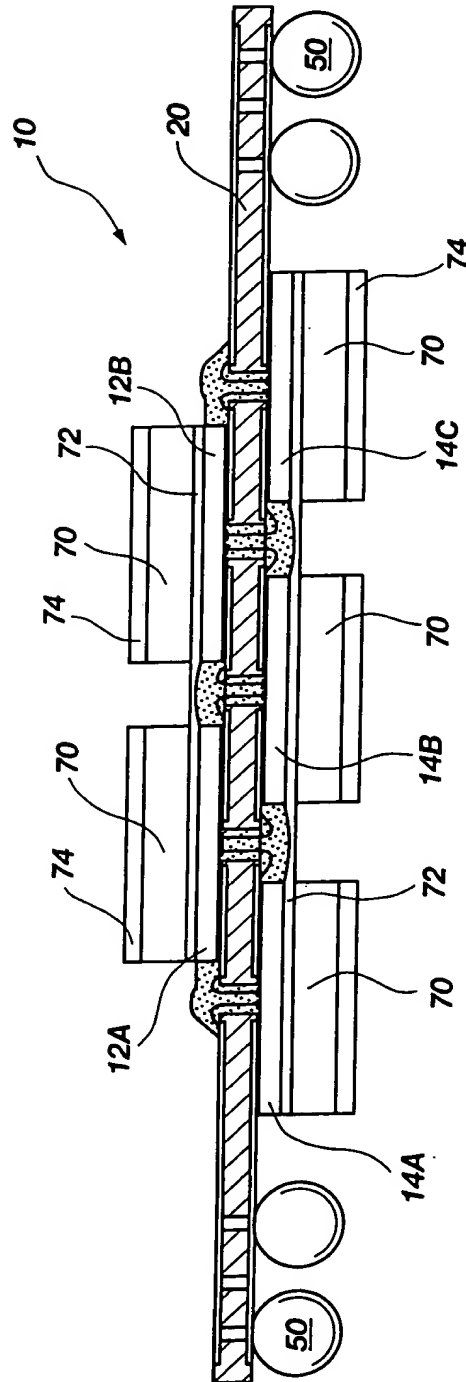


Fig. 15